IEC 61760-2

Edition 3.0 2021-07

INTERNATIONAL STANDARD

NORME INTERNATIONALE

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inside

Surface mounting technology –
Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide

Technique du montage en surface –
Partie 2: Conditions de transport et de stockage des composants pour montage en surface (CMS) – Guide d'application

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SURFACE MOUNTING TECHNOLOGY –

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FOREWORD

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IEC 61760-2 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1666/CDV	91/1708/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

Cross-references for references from this edition 3 to the previous edition 2 of this document are listed in Annex X of this document.

A list of all parts in the IEC 61760 series, published under the general title *Surface mounting technology*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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SURFACE MOUNTING TECHNOLOGY –

Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide

1 Scope

This International Standard specifies the transportation and storage conditions for surface mounting devices (SMDs) that are fulfilled in order to enable trouble-free processing of surface mounting devices, both active and passive. (Conditions for printed boards are not taken into consideration.)

The object of this document is to ensure that users of SMDs receive and store products that can be further processed (e.g. positioned, soldered) without prejudice to quality and reliability. Improper transportation and storage of SMDs can cause deterioration and result in assembly problems such as poor solderability, delamination and "popcorning".

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60721-3-1:2018, *Classification of environmental conditions – Part 3-1: Classification of groups of environmental parameters and their severities – Storage*

IEC 60721-3-2:2018, *Classification of environmental conditions – Part 3-2: Classification of groups of environmental parameters and their severities – Transportation and handling*

3 Terms and definitions

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

No terms and definitions are listed in this document.

4 General conditions

Surface mounting devices shall be packed in such a way that products are protected during transportation and storage without loss of their properties arising from mechanical, environmental and electrical influences. Packing requirements as defined in various IEC publications, such as IEC 60286-3, IEC 60286-4, IEC 60286-5, IEC 60286-6 and IEC TR 61340-5-5 can contribute to the protection of components during transportation and storage.

If dry packing is specified and used, the IEC publications IEC 61760-4, IEC 60749-20-1 and IPC/JEDEC J-STD-033 should be consulted.